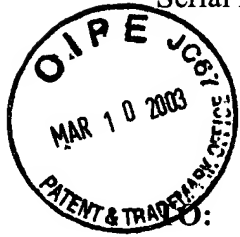


67,200-506; TSMC 00-804
Serial Number 09/920,911



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

DATE: 27 February 2003

REF: Applicant : Yu et al. Filing Date : 2 August 2001
Serial No : 09/920,911 Att'y No. : 67,200-506
Art Unit : 2812 Examiner : Richard A. Booth
Title : Thermal Compensation Method for Forming Semiconductor
Integrated Circuit Microelectronic Fabrication

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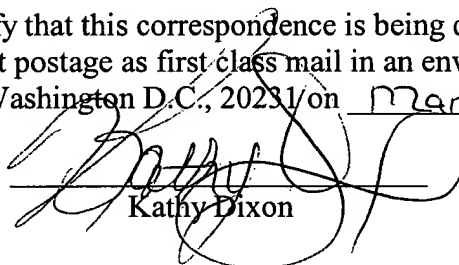
PRELIMINARY AMENDMENT

Sir:

In response to an advisory action mailed on 3 February 2003, and in conjunction with the appended request for continued examination, please consider the following remarks pertaining to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington D.C., 20231 on March 4 2003.


Kathy Dixon